TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $\pi$ -MOSV)

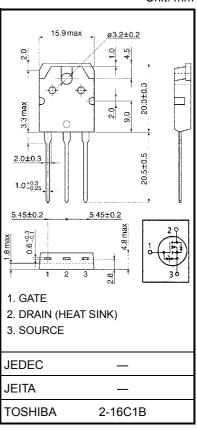
# 2SK2398

#### DC-DC Converter and Motor Drive Applications

- Low drain-source ON resistance  $: R_{DS}(ON) = 22 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance  $|Y_{fs}| = 27 \text{ S (typ.)}$
- Low leakage current  $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 60 \ V)$
- Enhancement-mode :  $V_{th} = 1.5 \sim 3.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA})$

#### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	60	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		V <sub>DGR</sub>	60	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	45	А	
	Pulse (Note 1)	I <sub>DP</sub>	180	А	
Drain power dissipation (Tc = 25°C)		PD	100	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	246	mJ	
Avalanche current		I <sub>AR</sub>	45	А	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	10	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	



Weight: 4.6 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch−c)</sub>	1.25	°C / W
Thermal resistance, channel to ambient	R <sub>th (ch−a)</sub>	50	°C / W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD} = 25 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C}$  (initial), L = 165 µH,  $R_G = 25 \Omega$ ,  $I_{AR} = 45 \text{ A}$ Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution. Unit: mm

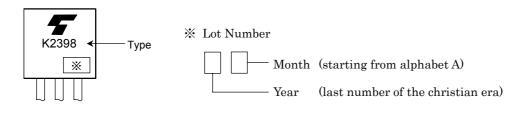
Electrical Characteristics (Ta = 25°C)

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	te leakage current $I_{GSS}$ $V_{GS} = \pm 16 V, V_{DS} = 0 V$		_	_	±10	μA	
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	_	_	100	μA
Drain-source br	rain-source breakdown voltage V (BR) DSS ID = 10 mA, VGS = 0 V		I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	60			V
Gate threshold v	e threshold voltage $V_{\text{th}}$ $V_{\text{DS}}$ = 10 V, I <sub>D</sub> = 1 mA		V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.5		3.0	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 25 A		22	30	mΩ
Forward transfe	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 25 A		27	_	S
Input capacitance	e	C <sub>iss</sub>			1800	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		350	_	pF
Output capacitance		C <sub>oss</sub>			900	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{}_{0V} \prod_{O \\ C \\ F \\ F$	_	20	_	ns
	Turn-on time	t <sub>on</sub>		_	30	_	
	Fall time	t <sub>f</sub>		_	40	_	
	Turn-off time	t <sub>off</sub>	$V_{DD} \Rightarrow 30V$ Duty $\leq 1\%$ , t <sub>w</sub> =10 $\mu$ s	_	130	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	60		
Gate-source charge		Q <sub>gs</sub>	V <sub>DD</sub> ≈ 48 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 45 A		40		nC
Gate-drain ("miller") charge		Q <sub>gd</sub>			20	—	

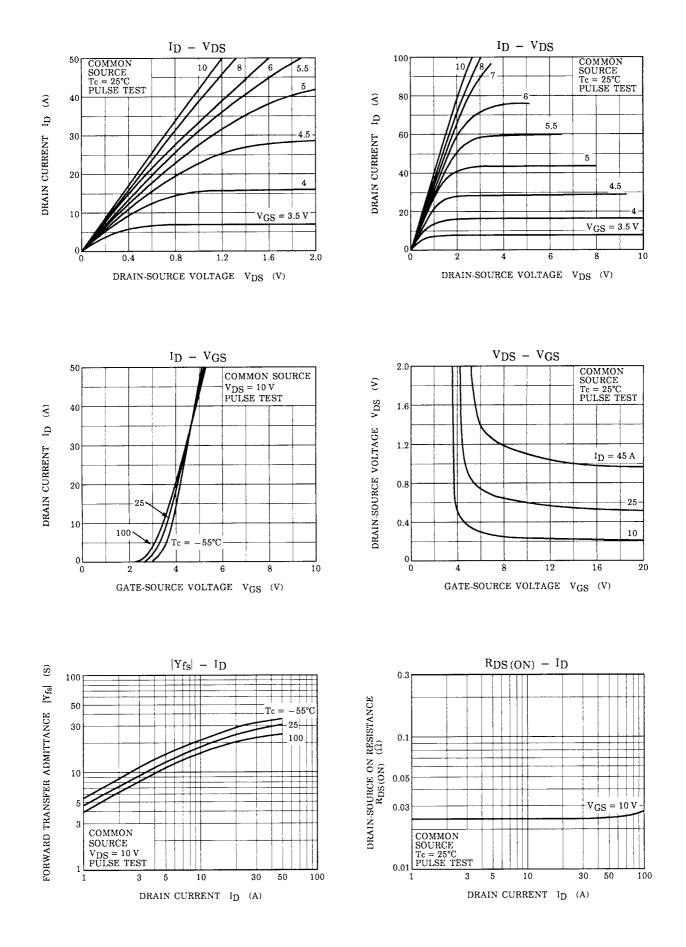
## Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	—	_	_	45	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	180	A
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 45 A, V <sub>GS</sub> = 0 V	_	_	-1.8	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 45 A, V <sub>GS</sub> = 0 V		60	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> / dt = 50 A / μs		51	—	nC

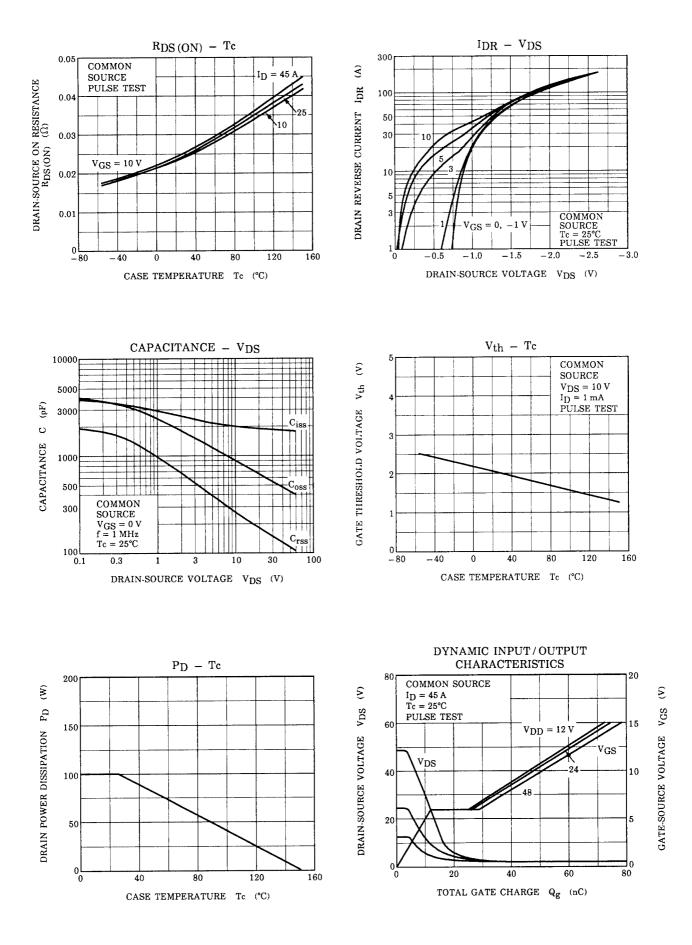
## Marking

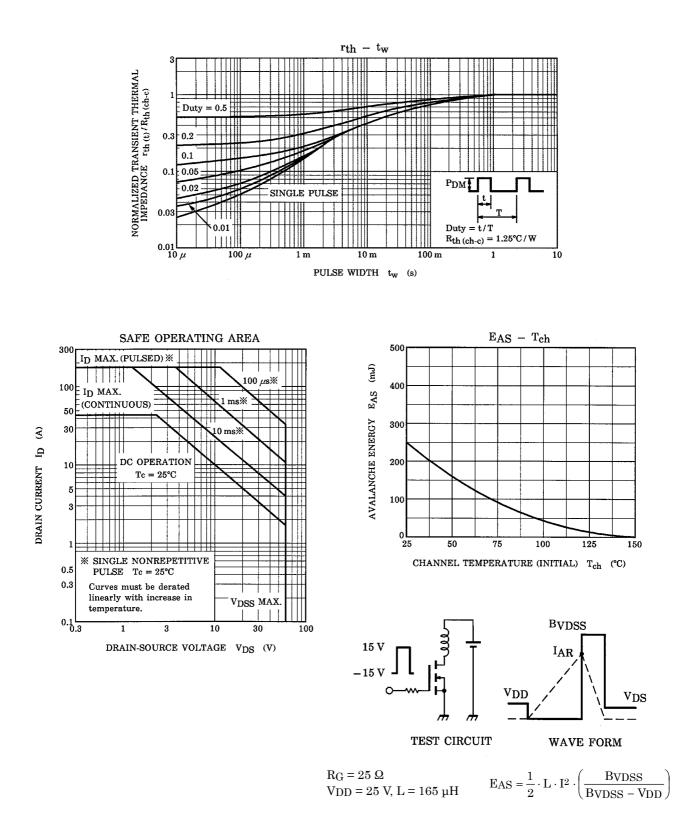


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